

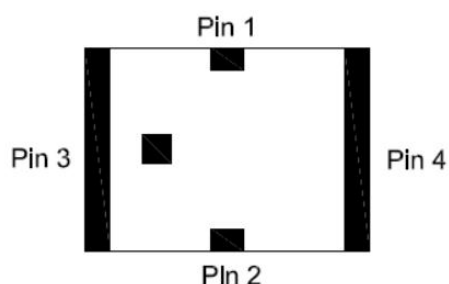
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

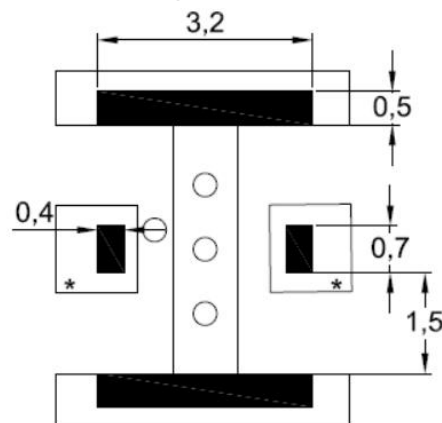
NO.	Parameter	Frequency (MHz)	SPC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)	1475~1675			2.7
2	VSWR				1.7
3	Attenuation (dB)	5~1350	34		
		1800	15		
		2300~3000	30		
4	In/Output Impedance (Ω)			75	
5	Permissible Input Power (W)				3
Operating & Storage Condition (Component) Operation Temperature Range: -40°C ~ +85°C Storage Temperature Range: -40°C ~ +85°C					
Storage Condition before Soldering (Included packaging material) Storage Temperature Range: +5 ~ +40 °C Humidity: 30 to 70% relative humidity					

Construction



PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

Mounting Considerations

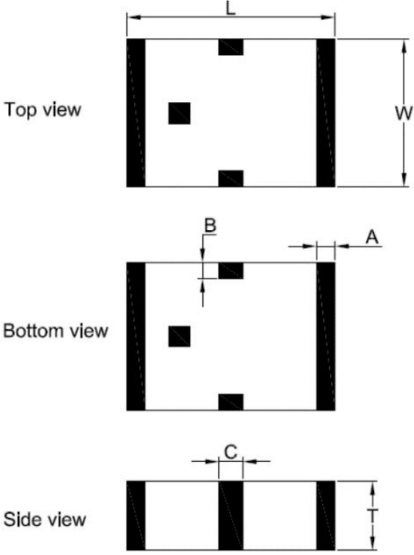


* Line width should be designed to match 75 Ω

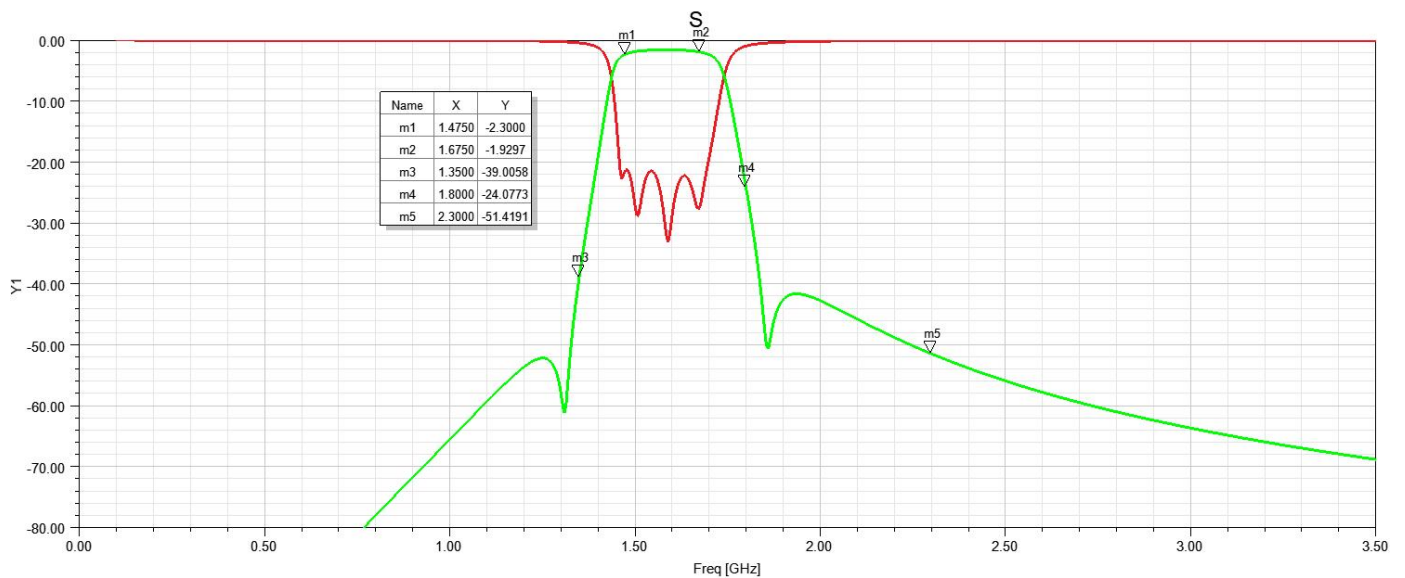
○ Through-hole (Φ 0.30)

Unit: mm

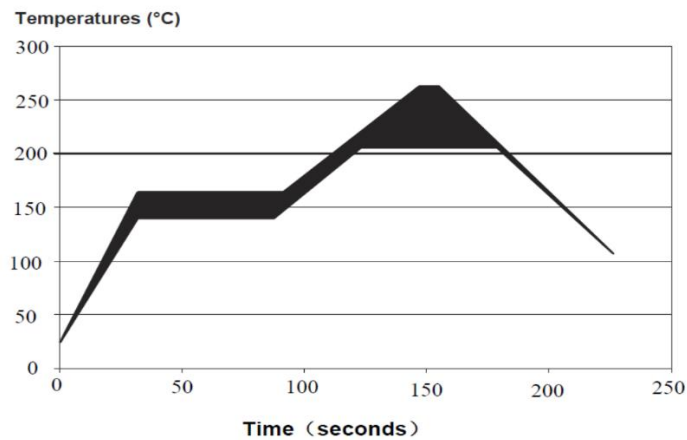
Dimensions

Figure	Symbol	Dimension (mm)
 Top view Bottom view Side view	L	4.50±0.20
	W	3.20±0.20
	T	1.50±0.10
	A	0.40±0.10
	B	0.35±0.10
	C	0.5±0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.